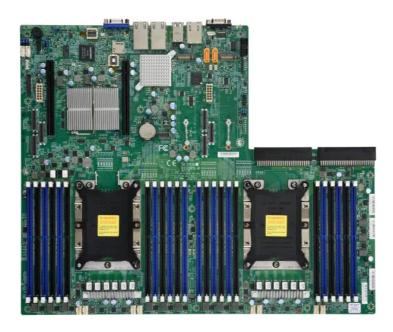
X11DPS-RE (For SuperServer Only)



NVMe 3 UPI Intel Quick Assist Technology

Key Features

- 1. 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors

 Dual Socket LGA-3647 (Socket P) supported, CPU TDP support Up to 205W TDP, 3 UPI up to 10.4 GT/s
- 2. Intel® C627
- 3. Up to 6TB 3DS ECC RDIMM, DDR4-2933MHz; Up to 6TB 3DS ECC LRDIMM, DDR4-2933MHz, in 24 DIMM slots; Up to 6TB Intel® Optane™ DC Persistent Memory in memory mode (Cascade Lake only)
- 4. 2 PCI-E 3.0 x16 (Low Profile), 4 PCI-E 3.0 x16

M.2 Interface: 2 PCI-E 3.0 x2 **M.2 Form Factor:** 2260/2280/22110

M.2 Key: M-Key

*2 SATA Hybrid ports, RAID 0 & 1

- 5. Dual LAN with 10GBase-T with Intel® X550
- 6. 1 VGA D-Sub Connector port

Specifications

Expansion Slots

M.2	PCI-E	2 PCI-E 3.0 x16 (Low Profile),4 PCI-E 3.0 x16
■ *2 SATA Hybrid ports, RAID 0 & 1	M.2	Form Factor: 2260/2280/22110

System BIOS

BIOS Type • AMI UEFI

Management

Software	SuperDoctor® 5, NMI, <u>SUM</u> , KVM with dedicated LAN, <u>SPM</u> , Intel® Node Manager, <u>SSM</u> , <u>IPMI2.0</u> , Watchdog, IPMI (Intelligent Platform Management Interface) v2.0 with KVM support
System Management Software	IPMI (Intelligent Platform Management Interface) v1.5 / 2.0 with KVM support
Power Configurations	■ ACPI Power Management

PC Health Monitoring

Voltage	■ VBAT, Monitors CPU voltages, Chipset Voltage, +5V standby, +5V, +3.3V, +12V, +1.8V, Memory Voltages
LED	UID/Remote UIDCPU / System Overheat LED
Temperature	 Monitoring for CPU and chassis environment
FAN	 8x 4-pin fan headers (up to 8 fans) System level control PWM fan speed control Status monitoring for speed control 8x fans with tachometer monitoring
Other Features	■ WOL, UID, System level control, RoHS, Node Manager Support, CPU thermal trip support for processor protection, Control of power-on for recovery from AC power loss, Chassis intrusion header, Chassis intrusion detection, RoHS, Halogen Free, Intel® QuickAssist Technology, Innovation Engine

Operating Environment

Operating	■ 10°C - 35°C (50°F - 95°F)
Temperature	
Range	

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MBD-X11DPS-	X11DPS-RE
RF	

Physical Stats

Form Factor	Proprietary	
Dimension	■ 13.5" x 16.73" (34.29cm x 42.49cm)	

Processor

CPU	 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors Dual Socket LGA-3647 (Socket P) supported, CPU TDP supports Up to 205W TDP, 3 UPI up to 10.4 GT/s
Note	 *2933 MHz in two DIMMs per channel can be achieved by using memory purchased from Supermicro

System Memory

Memory Capacity	 24 DIMM slots Up to 6TB 3DS ECC LRDIMM, DDR4-2933MHz; Up to 6TB 3DS ECC RDIMM, DDR4-2933MHz Up to 6TB Intel® Optane™ DC Persistent Memory in memory mode (Cascade Lake only)
Memory Type	2666/2400/2133MHz ECC DDR4 LRDIMM (3DS), RDIMM (3DS)
DIMM Sizes	■ LRDIMM: 64GB, 128GB ■ RDIMM: 32GB, 64GB, 128GB
Memory Voltage	" 1.2V
Error Detection	Corrects single-bit errorsDetects double-bit errors (using ECC memory)

On-Board Devices

Chipset	■ Intel® C627	
IPMI	■ ASPEED AST2500	
Graphics	■ ASPEED AST2500 BMC	
Network Controllers	■ Dual LAN with 10GBase-T with Intel® X550	

Input / Output

LAN	■ 2 RJ45 10GBase-T ports		
USB	■ 2 USB 3.0 port(s) (2 rear)		
Video Output	1 VGA D-Sub Connector port(s)		
Serial Port	2 COM Port(s) (1 header; 1 rear)		
DOM	2 Super <u>DOM</u> (Disk on Module) port with build power		
TPM	■ 1 TPM Header		

Non-Operating Temperature Range	■ -30°C - 60°C (-22°F - 140°F)
Operating Relative Humidity Range	■ 8% - 90% (non-condensing)
Non Operating Relative Humidity Range	■ 5% - 95% (non-condensing)

Parts List

Parts List (Bulk Package)				
Name	Part Number	Qty	Description	
Motherboard	MBD-X11DPS-RE	1	X11DPS-RE Motherboard	

Optional Parts List				
Name	Part Number	Qty	Description	
TPM security module (optional, not included)	<u>AOM-TPM-9670V</u>		SPI capable TPM 2.0 with Infineon 9670 controller with vertical form factor	

Server (Optimized for X11DPS-RE)

Server Name
SSG-1029P-NEL32R
SYS-1029P-N32R

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